

Title (en)

ELECTRONIC PACKAGE SEALED WITH A DISPENSABLE ADHESIVE.

Title (de)

ELEKTRONIKGEHAUSE, DAS MIT EINEM VERTEILBAREN KLEBSTOFF VERSIGELT WIRD.

Title (fr)

COMPOSANT ELECTRONIQUE SCELLE A L'AIDE D'UN ADHESIF EN DISTRIBUTEUR.

Publication

**EP 0673547 A1 19950927 (EN)**

Application

**EP 94901644 A 19931122**

Priority

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- US 98786792 A 19921209

Abstract (en)

[origin: WO9414193A1] There is provided a method for the assembly of an electronic package (48) utilizing liquid adhesives (30, 46). A first liquid adhesive (30) is dispensed on a base (12) and a leadframe (16) is supported by the liquid adhesive (30). A second liquid adhesive (46) is dispensed, overlying the first liquid adhesive (30) and the leadframe (16), and supports a cover (14). The entire assembly is then thermally cured. Means to control the flow of the liquid adhesives (52) and to reduce the mutual inductance between leads (72) are also provided.

IPC 1-7

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IPC 8 full level

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